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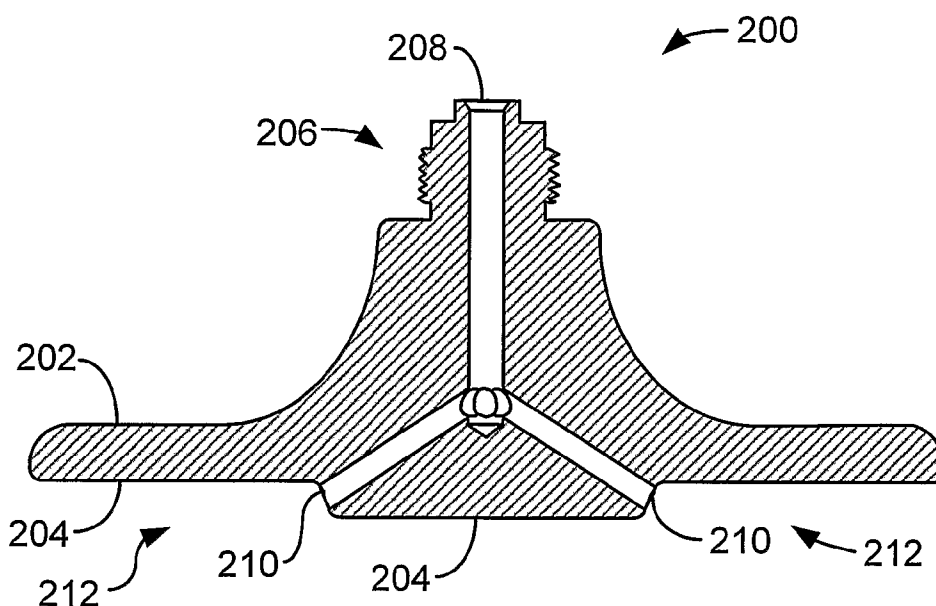
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(54) Title: GAS BAFFLE AND DISTRIBUTOR FOR SEMICONDUCTOR PROCESSING CHAMBER



(57) Abstract: Techniques of the present invention are directed to distribution of deposition gases onto a substrate. In one embodiment, a gas distributor (200) for use in a processing chamber (813) is provided. The gas distributor includes a body having a gas deflecting surface (202) and a gas distributor face (204). The gas deflecting surface defines a cleaning gas pathway. The gas distributor face is disposed on an opposite side of the body from the gas deflecting surface and faces toward a substrate support member (818). The gas distributor face includes a raised step (212) and at least one set of apertures (210) through the raised step. The at least one set of apertures are adapted to distribute a deposition gas over a substrate (817) positioned on the substrate support member.

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